ABSTRACT

INTEGRATED CIRCUIT SYSTEM EMPLOYING GRAIN SIZE ENLARGEMENT

An integrated circuit system that includes: providing a substrate including an active device with a gate top surface exposed; implanting a dopant within the gate to alter the grain size of the gate material; forming a dielectric layer over the active device and the substrate; and annealing the integrated circuit system to transfer the stress of the dielectric layer into the active device.

FIG. 4